



*The Institute for
Interconnecting
and Packaging
Electronic Circuits*

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Design Standard for Thick Film Multilayer Hybrid Circuits

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Standardization

In May 1995 the IPC's Technical Activities Executive Committee adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:

- Show relationship to DFM & DFE
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feed back system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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The material in this standard was developed by the Hybrid Design Task Group of the Hybrid & Related Technologies Committee of the Institute for Interconnecting and Packaging Electronic Circuits.

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